**Association of Powder Process Industry and Engineering, JAPAN**

図形, 円

自動的に生成された説明**Modeling and Simulation Division**

**APPIE Computational Granular Mechanics Award 2026**

Send a **single** electronic (PDF file preferred) copy of this form, supplemental sheets, supporting letters and other relevant documents via email to: **Modeling and Simulation (M&S) Division Secretariat.**

E-mail: [award@funtai.jp](mailto:award@funtai.jp)

**Deadline for complete package: January 31, 2026**

# Registration information

|  |  |
| --- | --- |
| **Name of Nominee** |  |
| **Present Position** |  |
| **Institution** |  |
| **Telephone Number** |  |
| **Email** |  |
| **Address** |  |
| **Education (Degree, Major, Year)** |  |

Date \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Nominator’s Signature\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

|  |  |
| --- | --- |
| **Selected bibliography** | |
| **Selected papers**  **(Max.10)** |  |
| **Selected invited lectures**  **(Max.10)** |  |
| **Awards, Other Contributions** |  |

**SUPPORTING LETTERS**

Letters from two individuals, whose names are listed below.

|  |  |
| --- | --- |
| **Name** | **Affiliation** |
|  |  |
|  |  |

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**M&S Division Secretariat** E-mail: [award@funtai.jp](mailto:award@funtai.jp)

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